imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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	RECOMMEN FINISHEE FINISHEE DRILLED COPPER F	NDED PRINTED) HOLE TIN PL) HOLE BARE (HOLE: Ø0.65 PLATING THICK	CIRCUIT BO ATING: Ø0. COPPER: Ø0. ±0.02 (NESS (MAX B	ARD HOLE [56±0.05 575±0.05 HARDNESS	DIMENSION	S FOR COMPLI)· 0 025-0 (ANT TAILS:	
	TIN PLAT ORGANIC	FING THICKNES SOLDERABILI	SS (MIN): O FY PRESERVA	.0038-0.0 TIVE (OSP)	124): USE WI	TH BARE COPF	PER.	
$\mathbf{)}$	2 PC BOARD) THICKNESS	.6mm MINIMU	UM.				
	DAUGHTEF PLATED F COPPER L TO PREVE	RCARD PC BOAF PAD SAND OPT AYERS TYPICA ENT COPPER ED	RD THICKNESS IONAL PCB EI AL FOR POWER OGE FROM ENG	SISI.6mm DGE CHAMFE R APPLICA GAGING BEF	m ± 10%. ERS ARE B TIONS AND FORE PCB	DIMENSION FR ASED ON 2 OZ Imm PCB PRC SUBSTRATE MA	ROM PCB EDGE TO 2. MAX. THICK DFILE CHAMFER ATERIAL.)
	👍 26.90mm	to ¢of adja	CENT CROWN	EDGE CONN	ECTOR.			
	5. MATERIAL	L: HOUSING AN CONTACTS:	ND OVERMOLDS Copper Alls	S: LCP, BL dy.	_ACK, UL9	4V-0 RATED		
	6 FINISH:	MATING AREA-	- 0.76µM MII	N. GOLD ON Gold on	VER 3.81 Nadiacen	MICROMETER N t flat sides	AIN. NICKEL PLA S in mating are	ιΤΕ.
		COMPLIANT P NICKEL PLATE WITH BELLCOF GR-I2I7-CORE	IN AREA- I.2 E. MATING AF RE APPROVED E ISSUE I, 1	N. OOLD OT 27µM MIN. REA AND A[LUBRICAN ⁻ NOVEMBER	MATTE TI DJACAENT I. TECHNI 1995.	N PLATE OVEF FLAT SIDES L CAL REFERENC	R I.27µM MIN. UBRICATED CE	. ^ .
()	FINISH:	MATING AREA COMPLIANT P NICKEL PLATE WITH BELLCOP GR-1217-CORE	- I.27µM MII O.64µm MII IN AREA- I.2 E. MATING AF RE APPROVED E ISSUE I, I	N. GOLD ON N. GOLD ON 27µm MIN. REA AND AE LUBRICAN ⁻ NOVEMBER	VER 3.81µn NADJACEN MATTE TI DJACENT F T. TECHNI 1995.	M MIN. NICKE T FLAT SIDES N PLATE OVEF LAT SIDES LU CAL REFERENC	EL PLATE S IN MATING ARE R I.27µm MIN. JBRICATED CE	ΙΑ.
	FINISH:	MATING AREA COMPLIANT P NICKEL PLAT WITH BELLCC ISSUE I, NC	- 0.76µm MIN 0.076µm M IN AREA- I.2 FE. MATING DRE APPROVED DVEMBER I995	N. GOLD ON IN. GOLD (27µm MIN. AREA AND A D LUBRICAN 5.	VER I.27µn ON ADJACE MATTE TI ADJACAENT NT. TECHN	m MIN. NICKE NT FLAT SIDE N PLATE OVEF FLAT SIDES ICAL REFEREN	EL PLATE. S IN MATING AF I.27µm MIN. LUBRICATED NCE GR-I2I7-COF	₹EA. ₹E
	9.450 LBS Prevent	MAXIMUM FORC Housing DAMA	CE ALLOWED (Age.	ON TOP OF	HOUSING	DURING APPLI	CATION TO PCB	ТО
	FINISH:	MATING AREA COMPLIANT P NICKEL PLATE WITH BELLCOP GR-1217-CORE	- 2.54µM MII 0.64µm MII IN AREA- I.2 E. MATING AF RE APPROVED E ISSUE I, I	N. GOLD ON N. GOLD ON 27µm MIN. REA AND AE LUBRICAN ⁻ NOVEMBER	VER 3.81µm N ADJACEN MATTE TI DJACENT F T. TECHNIM 1995.	m MIN. NICKE T FLAT SIDES N PLATE OVEF LAT SIDES LU CAL REFERENC	EL PLATE S IN MATING ARE R I.27µm MIN. JBRICATED CE	ΙΑ.
	A PREPRODU	JCTION, FASR	REQUIRED					
	A PART NUM	MBER WITH PIN	NOMITTED, S	see table	FOR LOCA	TION		
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AMP 4805 REV 31MAR2000

1926088-5 WITH PIN 3,4,7,8,11,12 OMITTED











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·	A RELEASED PE B REV PER FCO	R ECO-08-025381 -10-004250	150CT2008 03MAR2010	RG PD RG MS
	BI REV PER ECO	- 15-015062	04FEB2016	SZ SZ
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PIN 30 PIN 29	SCAL	E 4:1 6.8 4.	8	5
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7,8,11,12			192608	38 - 5
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	<u>42R4709</u>		+92608	30 - Z 38 -
FD PIN	IBM PART NO	FINISH	PART	NO
FOR TYCO ELECTRONICS CORPORATION				\sim

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION. CHK DEFECTD Tyco Electronics Harrisburg, PA 17105-3608 **tyco** Electronics <u>n. reeser</u> TOLERANCES UNLESS OTHERWISE SPECIFIED: 06MAR2006 NAME APVD N. REESER PRODUCT SPEC ÉSEMBLY, CROWN EDGE, VERTICAL CARD EDGE, 30 SIGNAL POSITION 0 PLC ±0.25 1 PLC ±0.25 2 PLC ±0.13 3 PLC ±0.08 4 PLC ±-APPLICATION SPEC size cage code drawing no A | 00779 C-1926088 RESTRICTED T INISH -SCALE 3:1 SHEET 1 OF 2 REV B 2 USTOMER DRAWING

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PCB BOARD LAYOUT 🖄 COMPONENT SIDE SHOWN

AMP 4805 REV 31MAR2000



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THIS DRAWING IS A CONTROLLED DO IT IS SUBJECT TO CHANGE AND TH SHOULD BE CONTACTE DIMENSIONS: mm TERIAL

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UMENT FOR TYCO ELECTRONICS CORPORATION CONTROLLING ENGINEERING ORGANIZATION FOR THE LATEST REVISION.		dwn 06MAR2006 WM VAN SCYOC	tyco	Tyco Electronics	
		снк 06MAR2006 N. REESER	Electronics	Harrisburg, PA 17105-360	3
	OTHERWISE SPECIFIED:	APVD 06MAR2006 N. REESER	ASSEMBLY, CROWN	FDGE. VERTICAL	CARD
	0 PLC ±0.25 1 PLC ±0.25	PRODUCT SPEC	EDGE, 30	SIGNAL POSITION	0,1110
_	2 PLC ±0.13 3 PLC ±0.08	- APPLICATION SPEC		-	
	4 PLC ±- ANGLES ±1°0′	-	SIZE CAGE CODE DRAWING NO		RESTRICTED TO
	FINISH -	WEIGHT _	$A \mid 00779 \bigcirc 192$	26088	-
	-	CUSTOMER DRAWING		SCALE 3:1 SHEET OF	2 ^{Rev} B2

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